

**C.I.F**

FR4 Data Sheet :-

Test/Specification	FR4 Laminate Typical Values
Thermal Stress, Solder bath 288 deg. C	>60
Dimensional Stability, E-2/150	<0.04% Warp/fill <1.00% Bow/Twist
Flammability, Classification UL94	V0
Water Absorption E-1/105	0.10%
Peel Strength After Thermal Stress	11 lb./in After 10s/288 Deg. C
Flexural Strength	100,000 lbf/in ² Lengthwise 75,000 lbf/in ² Crosswise
Resistivity After Damp Heat Volume	10 ⁸ M ohms cm
Resistivity After Damp Heat Surface	10 ⁸ M ohms
Dielectric Breakdown. Parallel to laminate	>60KV
Dielectric Constant @ 1MHz	4.7
Dissipation Factor @ 1MHz	0.014
Q-Resonance @ 1 MHz	>75
Q-Resonance @ 50 MHz	>95
Arc Resistance	125 s
Glass Transition Temperature	135 Deg. C
Temperature Index	130 Deg. C
A Few Other Relevant Facts from other Sources	
Specific Gravity	1.8-1.9
Rockwell Hardness (M scale)	110
Coefficient of Thermal Expansion	11 microns/m/Deg.C Lengthwise 15 microns/m/Deg.C Crosswise
Thermal Conductivity	2.2-2.5 cal/h. cm Deg C